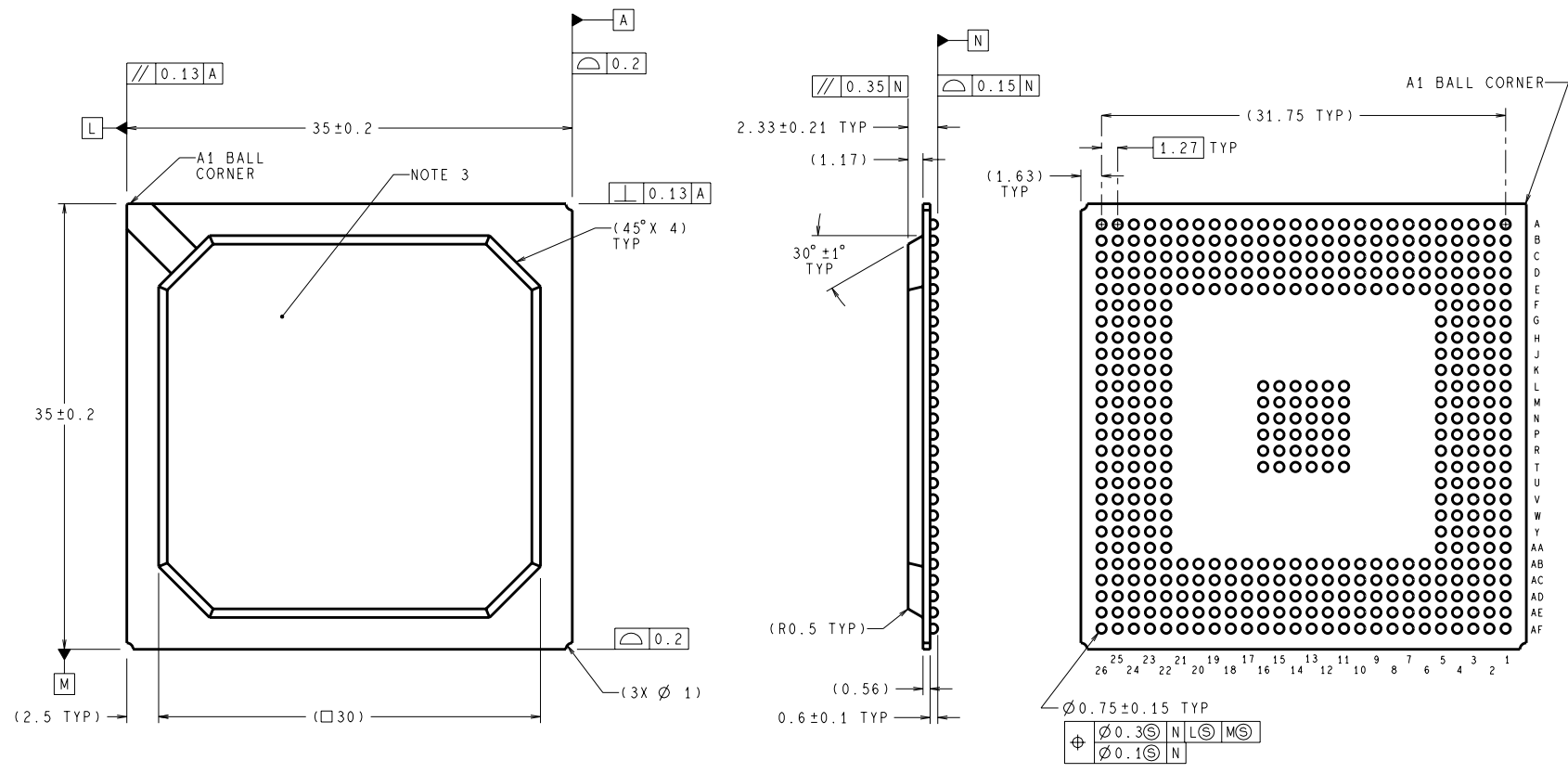


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12002	06/12/1998	TL/



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. THE MOLD SURFACE AREA MAY INCLUDE DIMPLE FOR A1 BALL CORNER IDENTIFICATION.
4. REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.27 PITCH, DATED JUNE 1997.
5. REFERENCE ASE'S PACKAGE OUTLINE DRAWING #64-06-A000-PB24.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN T. LEQUANG		06/12/1998			
DFTG. CHK.				PBGA, 35 X 35 X 2.33mm, 456 BALL, 1.27mm PITCH	
ENGR. CHK.					
 PROJECTION INCH (MM)		SCALE N/A	SIZE C	DRAWING NUMBER (ISC)MKT-UFB456A	REV A
DO NOT SCALE DRAWING				SHEET 1 of 1	